# LNJ926W8CRA

Surface-mounting Chip LED

UTSS Type

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Power dissipation	P <sub>D</sub>	70	mW	
Forward current	I <sub>F</sub>	20	mA	
Pulse forward current *	I <sub>FP</sub>	70	mA	
Reverse voltage	V <sub>R</sub>	5	V	
Operating ambient temperature	T <sub>opr</sub>	-30 to +85	°C	
Storage temperature	T <sub>stg</sub>	-40 to +100	°C	

Lighting Color

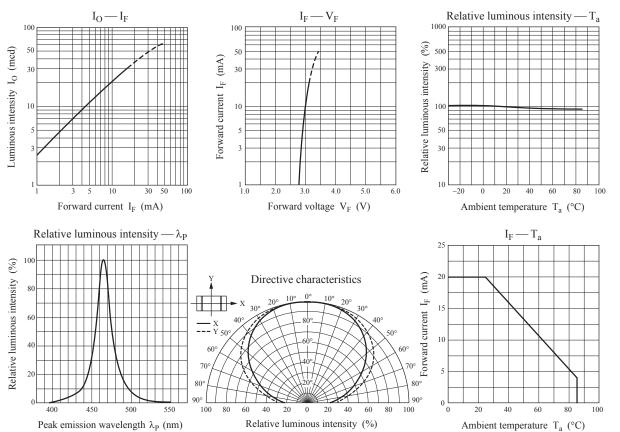
• Blue

Note) \*: The conditon of  $I_{FP}$  is duty 10%, pulse width 10 ms.

#### Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	Io	$I_F = 5 \text{ mA}$	8.5	11.5	24.6	mcd
Reverse current	I <sub>R</sub>	$V_R = 5 V$			100	μΑ
Forward voltage	V <sub>F</sub>	$I_F = 5 \text{ mA}$	2.65	2.90	3.15	V
Peak emission wavelength	$\lambda_{\rm P}$	$I_F = 5 \text{ mA}$		465		nm
Dominant emission wavelength	λ <sub>d</sub>	$I_F = 5 \text{ mA}$	462	470	478	nm
Spectral half band width	Δλ	$I_F = 5 \text{ mA}$		20		nm

Note) Be careful of the product destruction by static electricity.



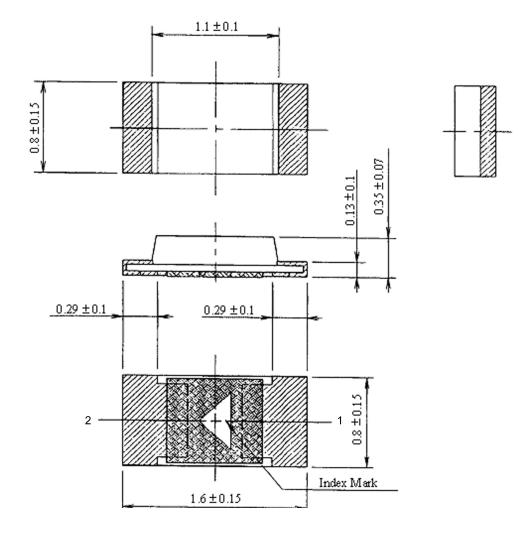
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### **Panasonic**

Package (Unit: mm)

### KLTFTN2K2600



• Pin name

1: Anode

2: Cathode

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